

16 Kbit (2K x 8) nvSRAM

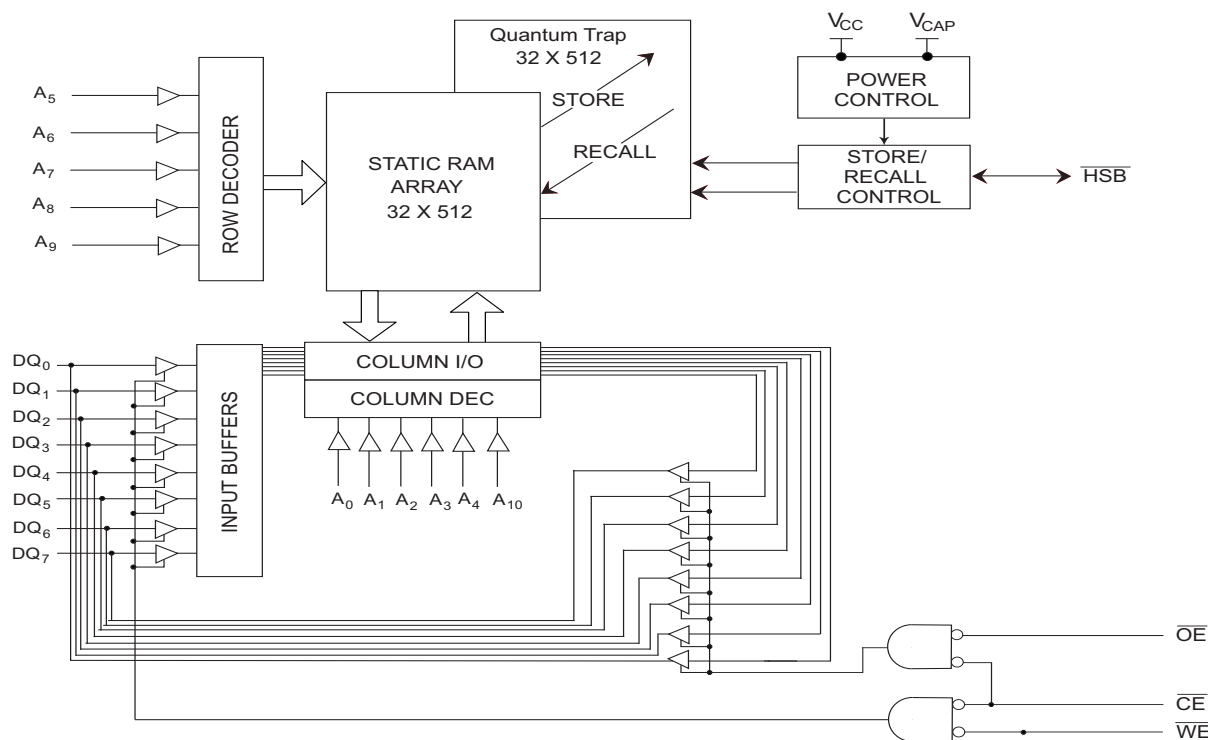
Features

- 25 ns, 35 ns and 45 ns access times
- Hands off automatic STORE on power down with external 68 μ F capacitor
- STORE to QuantumTrap™ non-volatile elements is initiated by hardware or AutoStore on power down
- RECALL to SRAM is initiated on power up
- Infinite READ, WRITE, and RECALL cycles
- 10 mA typical ICC at 200 ns cycle time
- 1,000,000 STORE cycles to QuantumTrap
- 100 year data retention to QuantumTrap
- Single 5V operation $\pm 10\%$
- Commercial and industrial temperature
- SOIC package
- RoHS compliance

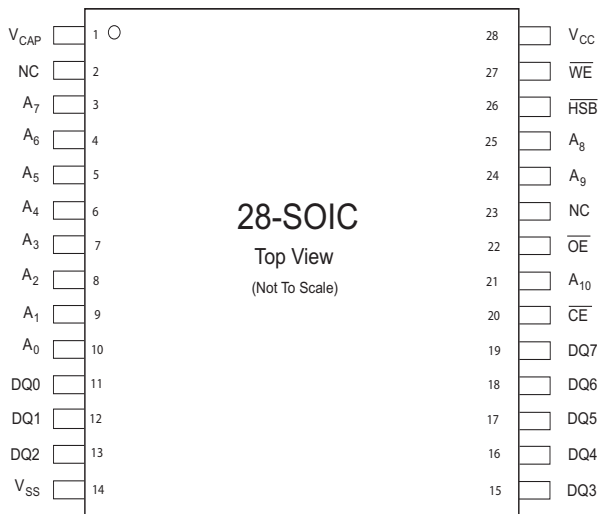
Functional Description

The Cypress CY22E016L is a fast static RAM with a non-volatile element incorporated in each static memory cell. The SRAM is read and written an infinite number of times, while independent, non-volatile data resides in non-volatile elements. Data transfers from the SRAM to the non-volatile elements (the STORE operation) takes place automatically on power down. A 68 μ F or larger capacitor tied from V_{CAP} to ground guarantees the STORE operation, regardless of power down slew rate or loss of power from "hot swapping." Transfers from the non-volatile elements to the SRAM (the RECALL operation) take place automatically on restoration of power. A hardware STORE is initiated with the HSB pin.

Logic Block Diagram



Pin Configurations



Pin Definitions

Pin Name	IO Type	Description
A_0 – A_{10}	Input	Address Inputs. Used to select one of the 2,048 bytes of the nvSRAM.
DQ0–DQ7	Input/Output	Bidirectional Data IO lines. Used as input or output lines depending on operation.
$\overline{WE}$	Input	Write Enable Input, Active LOW. When selected LOW, this writes data on the IO pins to the address location latched by the falling edge of $\overline{CE}$.
$\overline{CE}$	Input	Chip Enable Input, Active LOW. When LOW, selects the chip. When HIGH, deselects the chip.
$\overline{OE}$	Input	Output Enable, Active LOW. The active LOW $\overline{OE}$ input enables the data output buffers during read cycles. Deasserting $\overline{OE}$ HIGH causes the IO pins to tri-state.
V_{SS}	Ground	Ground for the Device. Is connected to ground of the system.
V_{CC}	Power Supply	Power Supply Inputs to the Device.
HSB	Input/Output	Hardware Store Busy (HSB). When LOW, this output indicates a Hardware Store is in progress. When pulled low external to the chip, it initiates a non-volatile STORE operation. A weak internal pull up resistor keeps this pin HIGH if not connected (connection optional).
V_{CAP}	Power Supply	AutoStore Capacitor. Supplies power to nvSRAM during power loss to store data from SRAM to non-volatile elements.
NC	No Connect	No Connects. This pin is not connected to the die.

Device Operation

The CY22E016L nvSRAM is made up of two functional components paired in the same physical cell. These are an SRAM memory cell and a non-volatile QuantumTrap cell. The SRAM memory cell operates as a standard fast static RAM. Data in the SRAM is transferred to the non-volatile cell (the STORE operation) or from the non-volatile cell to SRAM (the RECALL operation). This unique architecture enables storage and recall of all cells in parallel. During the STORE and RECALL operations, SRAM READ and WRITE operations are inhibited. The CY22E016L supports infinite reads and writes similar to a typical SRAM. In addition, it provides infinite RECALL operations from the non-volatile cells and up to one million STORE operations.

SRAM Read

The CY22E016L performs a READ cycle whenever $\overline{CE}$ and $\overline{OE}$ are LOW while $\overline{WE}$ and HSB are HIGH. The address specified on pins A_{0-10} determines which of the 2,048 data bytes are accessed. When the READ is initiated by an address transition, the outputs are valid after a delay of t_{AA} (READ cycle 1). If the READ is initiated by $\overline{CE}$ or $\overline{OE}$, the outputs are valid at t_{ACE} or at t_{DOE} , whichever is later (READ cycle 2). The data outputs repeatedly respond to address changes within the t_{AA} access time without the need for transitions on any control input pins, and remains valid until another address change or until $\overline{CE}$ or $\overline{OE}$ is brought HIGH, or $\overline{WE}$ or HSB is brought LOW.

SRAM Write

A WRITE cycle is performed whenever $\overline{CE}$ and $\overline{WE}$ are LOW and HSB is HIGH. The address inputs are stable prior to entering the WRITE cycle and must remain stable until either $\overline{CE}$ or $\overline{WE}$ goes HIGH at the end of the cycle. The data on the common IO pins IO_{0-7} is written into the memory if it is valid t_{SD} before the end of a $\overline{WE}$ controlled WRITE or before the end of a $\overline{CE}$ controlled WRITE. Keep $\overline{OE}$ HIGH during the entire WRITE cycle to avoid data bus contention on common IO lines. If $\overline{OE}$ is left LOW, internal circuitry turns off the output buffers t_{HZWE} after $\overline{WE}$ goes LOW.

AutoStore Operation

During normal AutoStore operation, the CY22E016L draws current from V_{CC} to charge a capacitor connected to the V_{CAP} pin. This stored charge is used by the chip to perform a single STORE operation. After power up, when the voltage on the V_{CAP} pin drops below V_{SWITCH} , the part automatically disconnects the V_{CAP} pin from V_{CC} and initiates a STORE operation.

Figure 1 shows the proper connection of the storage capacitor (V_{CAP}) for automatic store operation. A charge storage capacitor, having a capacity of between 68 μF and 220 μF ($\pm 20\%$) rated at 6V, is provided. In system power mode, both V_{CC} and V_{CAP} are connected to the +5V power supply without the 68 μF capacitor. In this mode, the AutoStore function of the CY22E016L operates

on the stored system charge as power goes down. The user must, however, guarantee that V_{CC} does not drop below 3.6V during the 10 ms STORE cycle..

Figure 1. AutoStore Mode

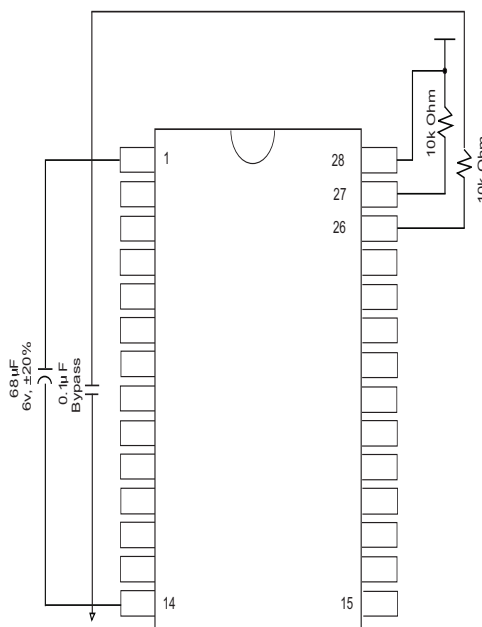
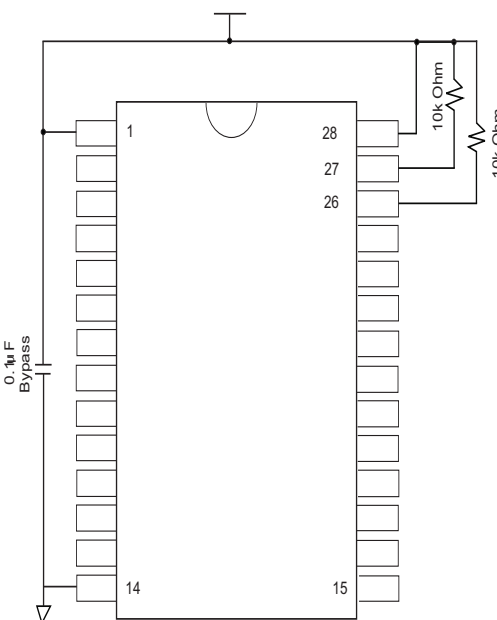


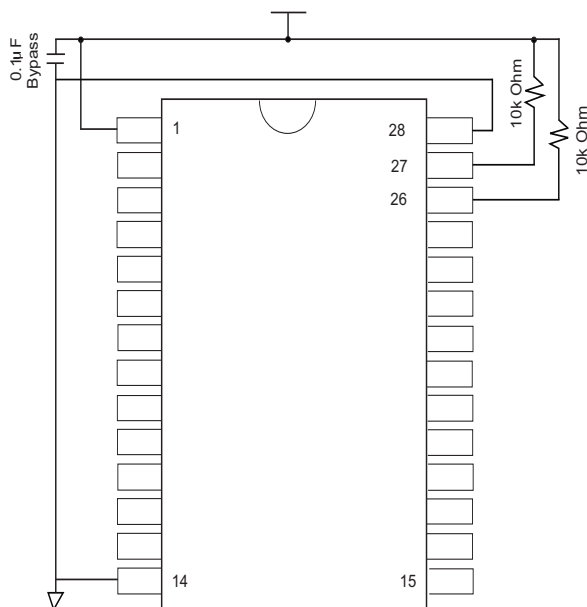
Figure 2. System Power Mode



If an automatic STORE on power loss is not required, then V_{CC} is tied to ground and +5V is applied to V_{CAP} . This is the AutoStore Inhibit mode where the AutoStore function is disabled. If the CY22E016L is operated in this configuration, references to V_{CC} are changed to V_{CAP} throughout this datasheet. In this mode, STORE operations are triggered with the HSB pin. It is not permissible to change between these three options at will.

To prevent unneeded STORE operations, automatic STORES and those initiated by externally driving HSB LOW are ignored, unless at least one WRITE operation takes place since the most recent STORE or RECALL cycle. An optional pull up resistor is shown connected to HSB. This is used to signal the system that the AutoStore cycle is in progress.

Figure 3. AutoStore Inhibit Mode



Hardware STORE (HSB) Operation

The CY22E016L provides the $\overline{HSB}$ pin for controlling and acknowledging the STORE operations. The $\overline{HSB}$ pin is used to request a hardware STORE cycle. When the HSB pin is driven low, the CY22E016L conditionally initiates a STORE operation after t_{DELAY} . An actual STORE cycle begins if a WRITE to the SRAM took place since the last STORE or RECALL cycle. The HSB pin also acts as an open drain driver that is internally driven low to indicate a busy condition, while the STORE (initiated by any means) is in progress.

SRAM READ and WRITE operations that are in progress when $\overline{HSB}$ is driven low by any means are given time to complete before the STORE operation is initiated. After HSB goes low, the CY22E016L continues SRAM operations for t_{DELAY} . During t_{DELAY} , multiple SRAM READ operations take place. If a WRITE is in progress when HSB is pulled LOW, it is allowed a time, t_{DELAY} , to complete. However, any SRAM WRITE cycles requested after HSB goes LOW are inhibited until $\overline{HSB}$ returns HIGH.

The $\overline{HSB}$ pin is used to synchronize multiple CY22E016L while using a single larger capacitor. To operate in this mode, the HSB

pin is connected together to the $\overline{HSB}$ pins from the other CY22E016L. An external pull up resistor to +5V is required, since HSB acts as an open drain pull down. The V_{CAP} pins from the other CY22E016L parts are tied together and share a single capacitor. The capacitor size is scaled by the number of devices connected to it. When any one of the CY22E016L detects a power loss and asserts HSB, the common HSB pin causes all parts to request a STORE cycle. (A STORE takes place in those CY22E016L that are written since the last non-volatile cycle.)

During any STORE operation, regardless of how it is initiated, the CY22E016L continues to drive the HSB pin LOW, releasing it only when the STORE is complete. After completing the STORE operation, the CY22E016L remains disabled until the HSB pin returns HIGH.

If HSB is not used, it is left unconnected.

Hardware RECALL (Power Up)

During power up or after any low power condition ($V_{CC} < V_{SWITCH}$), an internal RECALL request is latched. When V_{CC} once again exceeds the sense voltage of V_{SWITCH} , a RECALL cycle is automatically initiated and takes $t_{HRECALL}$ to complete.

Data Protection

The CY22E016L protects data from corruption during low voltage conditions by inhibiting all externally initiated STORE and WRITE operations. The low voltage condition is detected when V_{CC} is less than V_{SWITCH} . If the CY22E016L is in a WRITE mode (both CE and WE are LOW) at power up after a RECALL or after a STORE, the WRITE is inhibited until a negative transition on CE or WE is detected. This protects against inadvertent writes during power up or brown out conditions.

Noise Considerations

The CY22E016L is a high speed memory. It must have a high frequency bypass capacitor of approximately 0.1 μF connected between V_{CC} and V_{SS} , using leads and traces that are as short as possible. As with all high speed CMOS ICs, careful routing of power, ground, and signals reduces circuit noise.

Low Average Active Power

CMOS technology provides the CY22E016L the benefit of drawing significantly less current when it is cycled at times longer than 50 ns. Figure 4 shows the relationship between I_{CC} and READ/WRITE cycle time. Worst case current consumption is shown for both CMOS and TTL input levels (commercial temperature range, $V_{CC} = 5.5V$, 100% duty cycle on chip enable). Only standby current is drawn when the chip is disabled. The overall average current drawn by the CY22E016L depends on the following items:

1. The duty cycle of chip enable
2. The overall cycle rate for accesses
3. The ratio of READs to WRITEs
4. CMOS vs. TTL input levels
5. The operating temperature
6. The V_{CC} level
7. IO loading

Preventing STORES

The STORE function is disabled by holding $\overline{\text{HSB}}$ HIGH with a driver capable of sourcing 30 mA at a V_{OH} of at least 2.2V, because it has to overpower the internal pull down device. The device drives HSB low for 20 ns at the onset of a STORE. When the CY22E016L is connected for AutoStore operation (system

V_{CC} connected to V_{CC} and a 68 μF capacitor on V_{CAP}) and V_{CC} crosses V_{SWITCH} on the way down, the CY22E016L attempts to pull HSB LOW; if $\overline{\text{HSB}}$ does not actually get below V_{IL} , the part stops trying to pull HSB low and abort the STORE attempt.

Table 1. Hardware Mode Selection

$\overline{\text{CE}}$	$\overline{\text{WE}}$	$\overline{\text{HSB}}$	A10-A0	Mode	IO	Power
H	X	H	X	Not Selected	Output High Z	Standby
L	H	H	X	Read SRAM	Output Data	Active
L	L	H	X	Write SRAM	Input Data	Active
X	X	L	X	Non-volatile STORE	Output High Z	I_{CC2}

Figure 4. Current versus Cycle Time (READ)

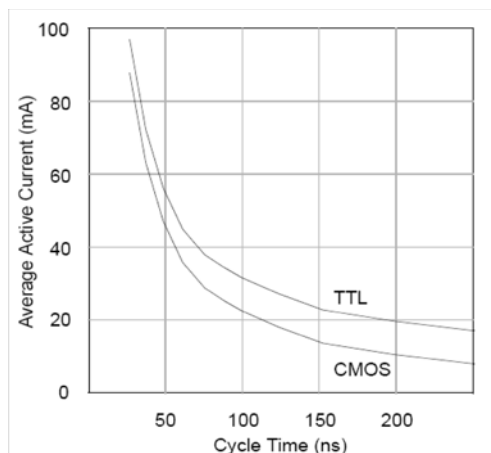
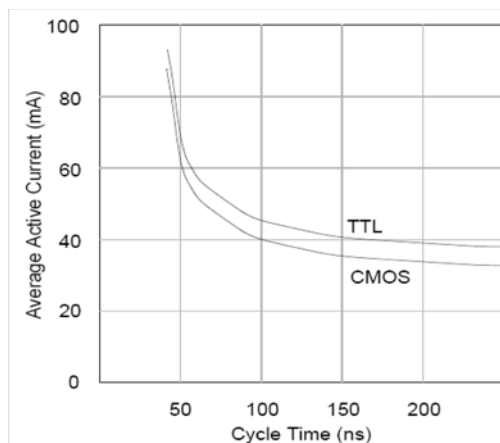


Figure 5. Current versus Cycle Time (WRITE)



Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. These user guidelines are not tested.

Storage Temperature -65°C to +150°C

Ambient Temperature with
Power Applied -55°C to +125°C

Supply Voltage on V_{CC} Relative to GND -0.5V to 7.0V

Voltage Applied to Outputs
in High Z State -0.5V to $V_{CC} + 0.5V$

Input Voltage -0.5V to $V_{CC} + 0.5V$

Transient Voltage (greater than 20 ns) on
Any Pin to Ground Potential -0.5V to $V_{CC} + 2.0V$

Package Power Dissipation
Capability ($T_A = 25^\circ\text{C}$) 1.0W

Surface Mount Lead Soldering
Temperature (3 Seconds) +260°C

Output Short Circuit Current ^[1] 15 mA

Static Discharge Voltage > 2001V
(MIL-STD-883, Method 3015)

Latch up Current > 200 mA

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0°C to +70°C	4.5V to 5.5V
Industrial	-40°C to +85°C	

DC Electrical Characteristics

Over the Operating Range ($V_{CC} = 4.5V$ to $5.5V$) ^[2]

Parameter	Description	Test Conditions	Min	Max	Unit
I_{CC1}	Average V_{CC} Current	$t_{RC} = 25\text{ ns}$ $t_{RC} = 35\text{ ns}$ $t_{RC} = 45\text{ ns}$ Dependent on output loading and cycle rate. Values obtained without output loads. $I_{OUT} = 0\text{ mA}$.	Commercial	85 75 65	mA mA mA
I_{CC2}	Average V_{CC} Current during STORE	All Inputs Do Not Care, $V_{CC} = \text{Max}$ Average current for duration t_{STORE}		3	mA
I_{CC3}	Average V_{CC} Current at $t_{AVAV} = 200\text{ ns}$, 5V, 25°C Typical	$\overline{WE} > (V_{CC} - 0.2)$. All other inputs cycling. Dependent on output loading and cycle rate. Values obtained without output loads.		10	mA
I_{CC4}	Average V_{CAP} Current during AutoStore Cycle	All Inputs Do Not Care, $V_{CC} = \text{Max}$ Average current for duration t_{STORE}		2	mA
I_{SB}	V_{CC} Standby Current	$\overline{CE} > (V_{CC} - 0.2)$. All others $V_{IN} < 0.2V$ or $> (V_{CC} - 0.2V)$. Standby current level after non-volatile cycle is complete. Inputs are static. $f = 0\text{ MHz}$.		2.5	mA
I_{ILK}	Input Leakage Current	$V_{CC} = \text{Max}$, $V_{SS} \leq V_{IN} \leq V_{CC}$	-1	+1	μA
I_{OLK}	Off State Output Leakage Current	$V_{CC} = \text{Max}$, $V_{SS} \leq V_{IN} \leq V_{CC}$, $\overline{CE}$ or $\overline{OE} > V_{IH}$	-5	+5	μA
V_{IH}	Input HIGH Voltage		2.2	$V_{CC} + 0.5$	V
V_{IL}	Input LOW Voltage		$V_{SS} - 0.5$	0.8	V
V_{OH}	Output HIGH Voltage	$I_{OUT} = -4\text{ mA}$ except HSB	2.4		V
V_{OL}	Output LOW Voltage	$I_{OUT} = 8\text{ mA}$ except HSB		0.4	V
V_{BL}	Logic '0' on HSB	$I_{OUT} = 3\text{ mA}$		0.4	V

Notes

- Outputs shorted for no more than one second. No more than one output shorted at a time.
- Typical conditions for the Active Current shown on the front page of the datasheet are average values at 25°C (room temperature) and $V_{CC} = 5V$. Not 100% tested.

Capacitance

These parameters are guaranteed but not tested.

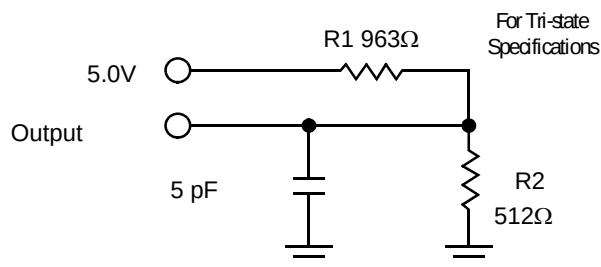
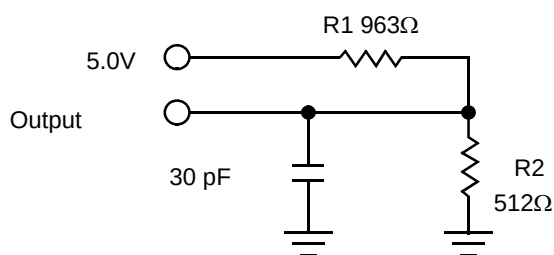
Parameter	Description	Test Conditions	Max	Unit
C_{IN}	Input Capacitance	$T_A = 25^\circ\text{C}$, $f = 1\text{ MHz}$, $V_{CC} = 0\text{ to }3.0\text{ V}$	8	pF
C_{OUT}	Output Capacitance		7	pF

Thermal Resistance

These parameters are guaranteed but not tested.

Parameter	Description	Test Conditions	28-SOIC	Unit
Θ_{JA}	Thermal Resistance (Junction to Ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, per EIA / JESD51.	TBD	$^\circ\text{C/W}$
Θ_{JC}	Thermal Resistance (Junction to Case)		TBD	$^\circ\text{C/W}$

AC Test Loads



AC Test Conditions

Input Pulse Levels.....0V to 3V
 Input Rise and Fall Times (10% - 90%)..... $\leq 5\text{ ns}$
 Input and Output Timing Reference Levels.....1.5V

AC Switching Characteristics

Parameter		Description	25 ns Part		35 ns Part		45 ns Part		Unit
Cypress Parameter	Alt. Parameter		Min	Max	Min	Max	Min	Max	
SRAM Read Cycle									
t _{ACE}	t _{ACS}	Chip Enable Access Time		25		35		45	ns
t _{RC} ^[4]	t _{RC}	Read Cycle Time	25		35		45		ns
t _{AA} ^[5]	t _{AA}	Address Access Time		25		35		45	ns
t _{DOE}	t _{OE}	Output Enable to Data Valid		10		15		20	ns
t _{OHA} ^[5]	t _{OH}	Output Hold After Address Change	5		5		5		ns
t _{LZCE} ^[6]	t _{LZ}	Chip Enable to Output Active	5		5		5		ns
t _{HZCE} ^[6]	t _{HZ}	Chip Disable to Output Inactive		10		13		15	ns
t _{LZOE} ^[6]	t _{OLZ}	Output Enable to Output Active	0		0		0		ns
t _{HZOE} ^[6]	t _{OHZ}	Output Disable to Output Inactive		10		13		15	ns
t _{PU} ^[3]	t _{PA}	Chip Enable to Power Active	0		0		0		ns
t _{PD} ^[3]	t _{PS}	Chip Disable to Power Standby		25		35		45	ns
SRAM Write Cycle									
t _{WC}	t _{WC}	Write Cycle Time	25		35		45		ns
t _{PWE}	t _{WP}	Write Pulse Width	20		25		30		ns
t _{SCE}	t _{CW}	Chip Enable to End of Write	20		25		30		ns
t _{SD}	t _{DW}	Data Setup to End of Write	10		12		15		ns
t _{HD}	t _{DH}	Data Hold After End of Write	0		0		0		ns
t _{AW}	t _{AW}	Address Setup to End of Write	20		25		30		ns
t _{SA}	t _{AS}	Address Setup to Start of Write	0		0		0		ns
t _{HA}	t _{WR}	Address Hold After End of Write	0		0		0		ns
t _{HZWE} ^[6,7]	t _{WZ}	Write Enable to Output Disable		10		13		14	ns
t _{LZWE} ^[6]	t _{OW}	Output Active After End of Write	5		5		5		ns

AutoStore Power Up RECALL

Parameter	Description	CY22E016L		Unit
		Min	Max	
$t_{HRECALL}^{[8]}$	Power up RECALL Duration		550	μ S
$t_{STORE}^{[9]}$	STORE Cycle Duration		10	ms
t_{DELAY}	Time Allowed to Complete SRAM Cycle	1		μ S
V_{SWITCH}	Low Voltage Trigger Level	4.0	4.5	V
V_{RESET}	Low Voltage Reset Level		3.6	V

Notes

- These parameters are guaranteed but not tested.
- IWE must be HIGH during SRAM Read Cycles.
- Device is continuously selected with CE and OE both Low.
- Measured ± 200 mV from steady state output voltage.
- If WE is Low when CE goes Low, the outputs remain in the high impedance state.
- $t_{HRECALL}$ starts from the time V_{CC} rises above V_{SWITCH} .
- If an SRAM Write has not taken place since the last non-volatile cycle, no STORE will take place

Hardware STORE Cycle

Parameter	Description	CY22E016L		Unit
		Min	Max	
$t_{STORE}^{[6]}$	STORE Cycle Duration		10	ms
$t_{DELAY}^{[10]}$	Time Allowed to Complete SRAM Cycle	1		ms
$t_{RESTORE}^{[11]}$	Hardware STORE High to Inhibit Off		700	ns
t_{HLHX}	Hardware STORE Pulse Width	15		ns
t_{HLBL}	Hardware STORE Low to STORE Busy		300	ns

Switching Waveforms

Figure 6. SRAM Read Cycle Number 1: Address Controlled [3, 5, 12]

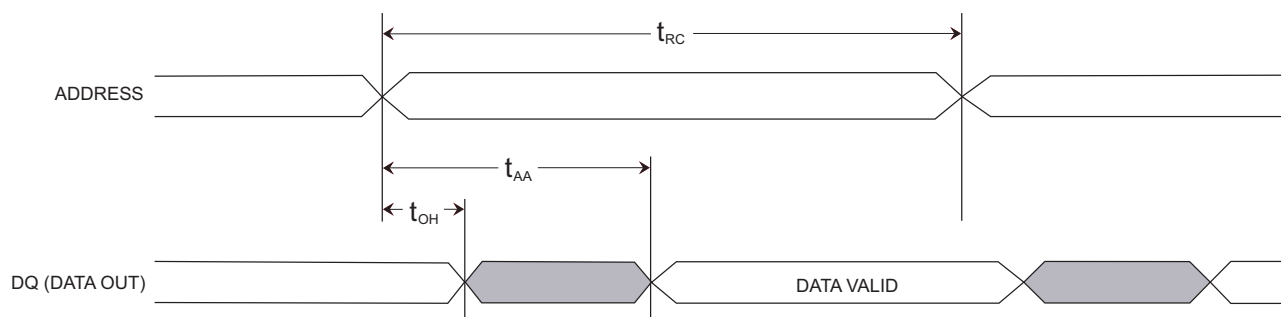
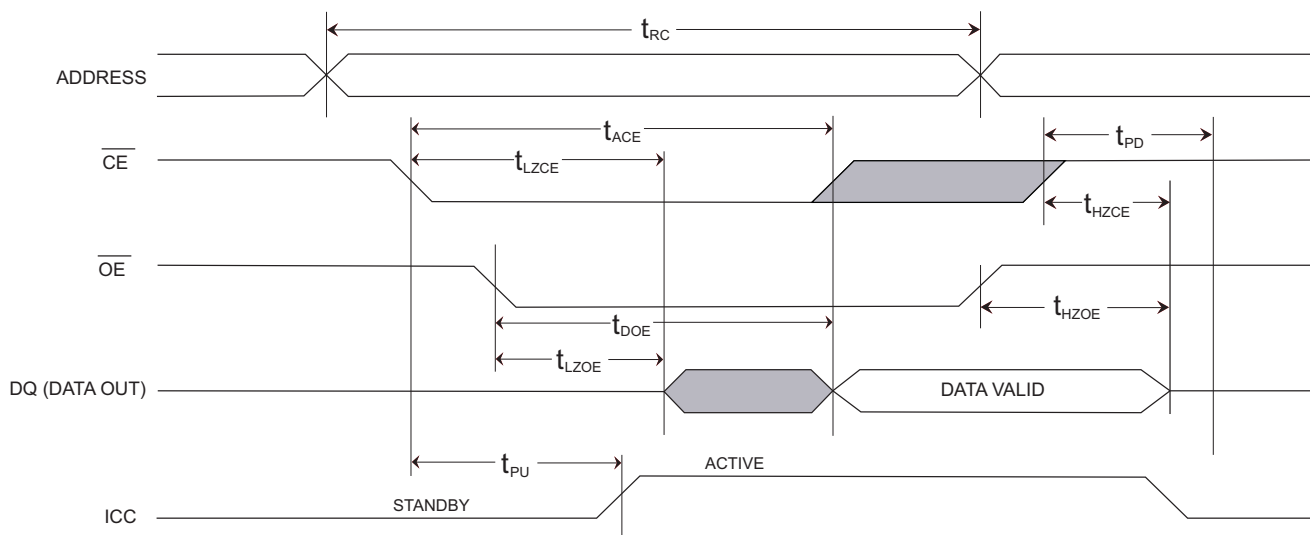


Figure 7. SRAM Read Cycle Number 2: $\overline{CE}$ Controlled [3,12]



Notes

10. Read and Write cycles in progress before $\overline{HSB}$ are given this amount of time to complete.
11. $t_{RESTORE}$ is only applicable after t_{STORE} is complete.
12. HSB must remain HIGH during READ and WRITE cycles.

Switching Waveforms (continued)

Figure 9. SRAM Write Cycle Number 1: $\overline{WE}$ Controlled [12,13]

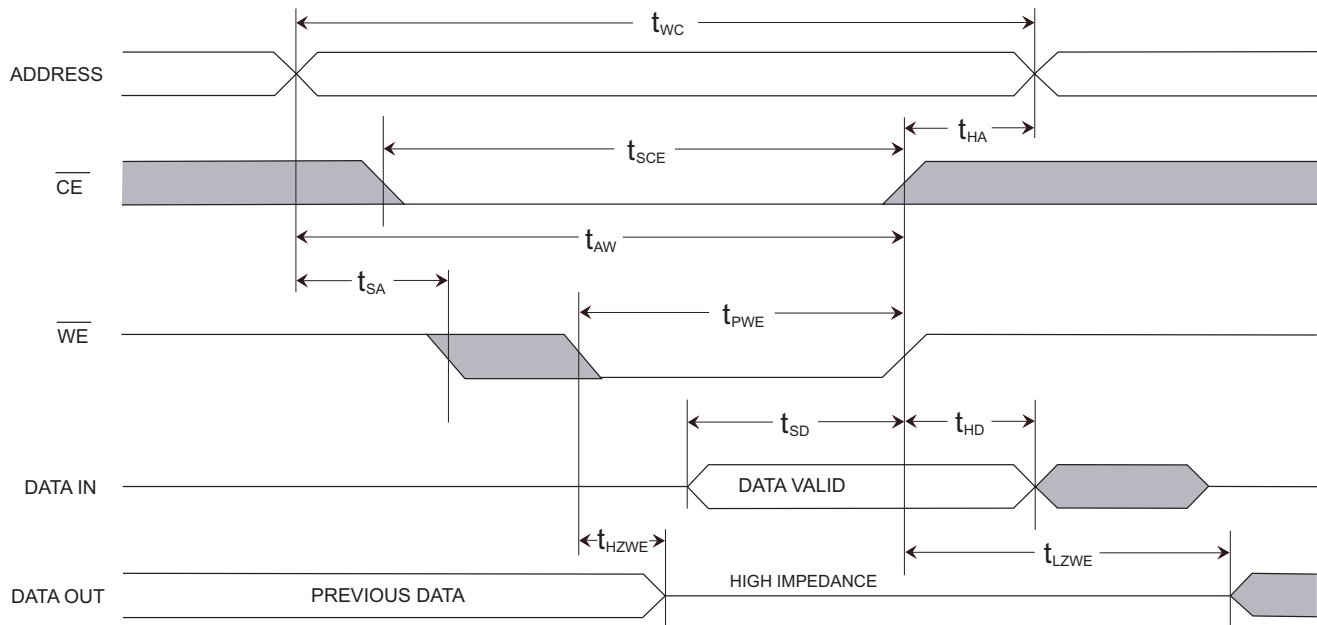
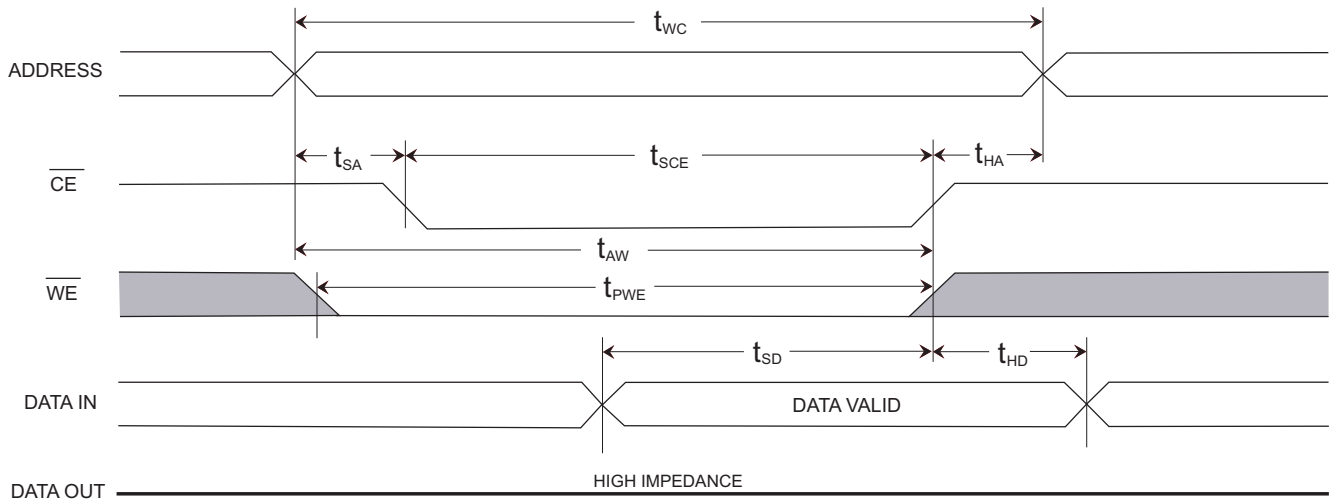


Figure 8. SRAM Write Cycle Number 2: $\overline{CE}$ Controlled



Note

13. $\overline{CE}$ or $\overline{WE}$ is less than V_{IH} during address transitions.

Switching Waveforms (continued)

Figure 10. AutoStore or Power Up RECALL

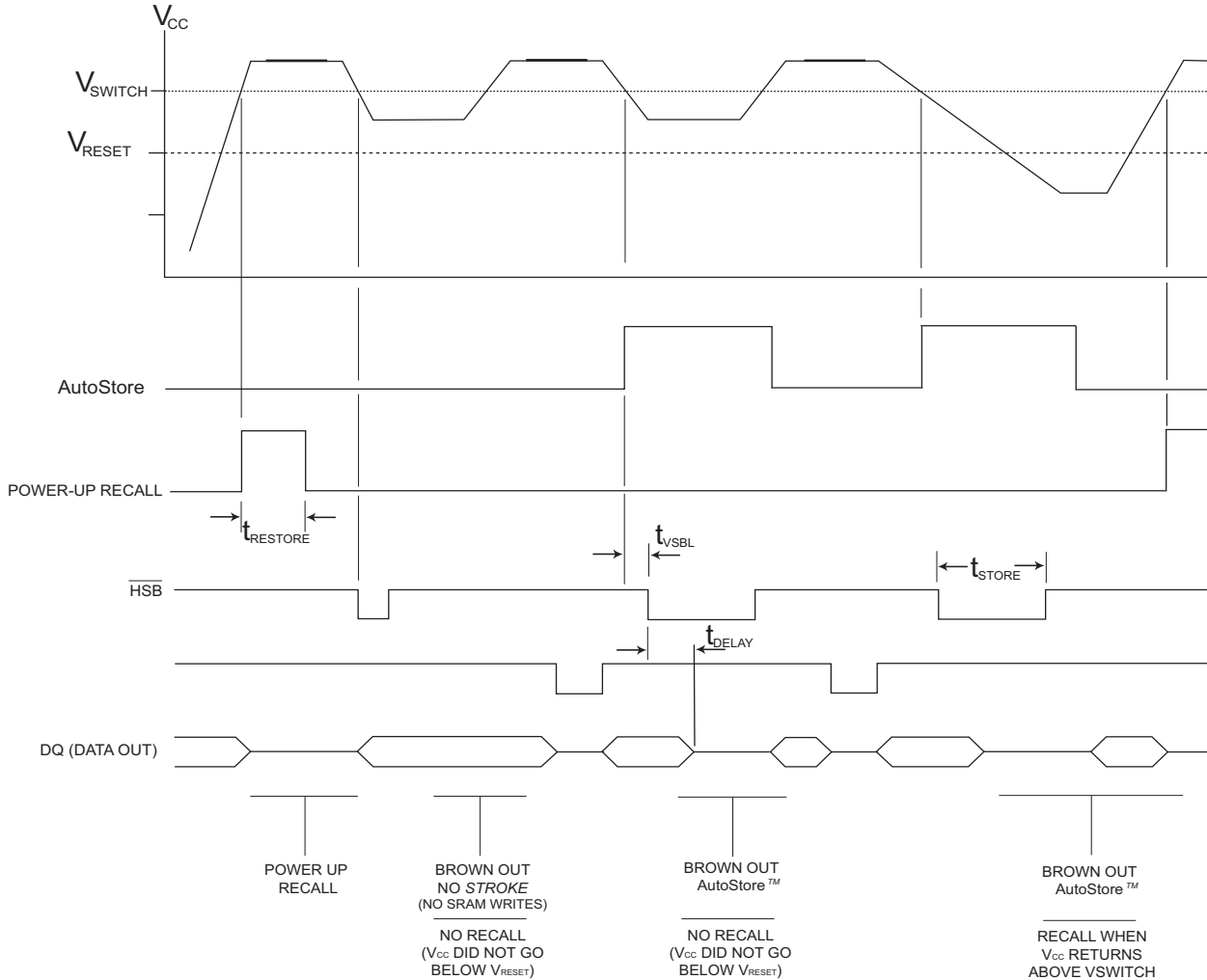
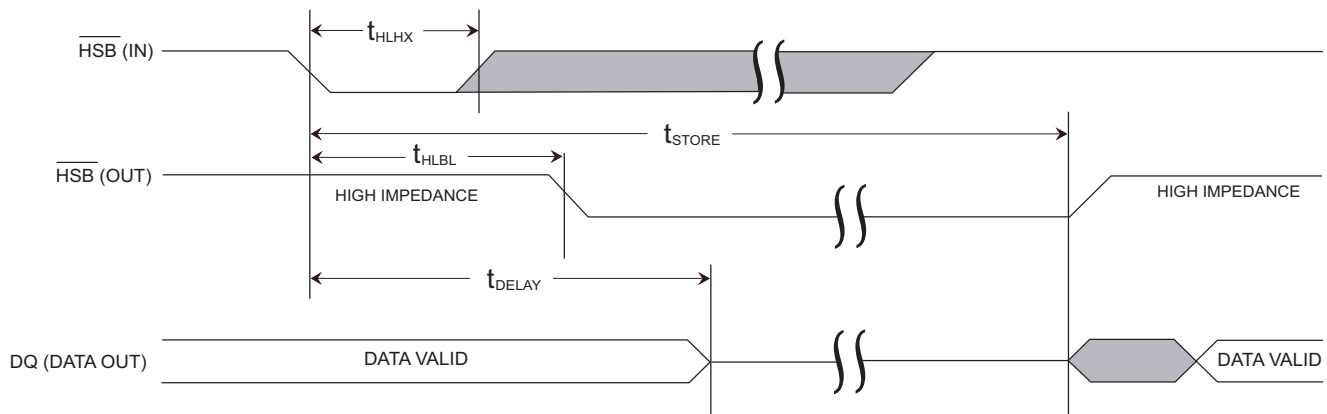
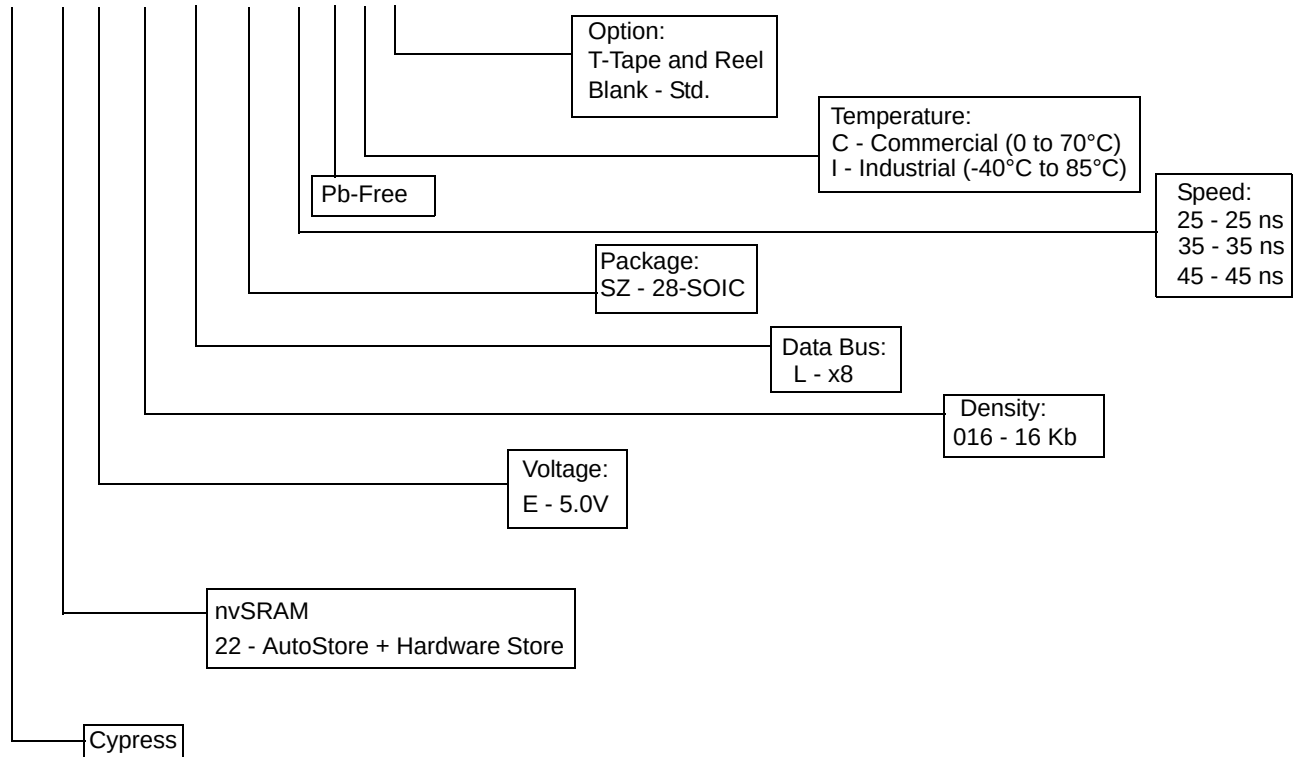


Figure 11. Hardware STORE Cycle



Part Numbering Nomenclature

CY 22 E 016 L- SZ 25 X C T



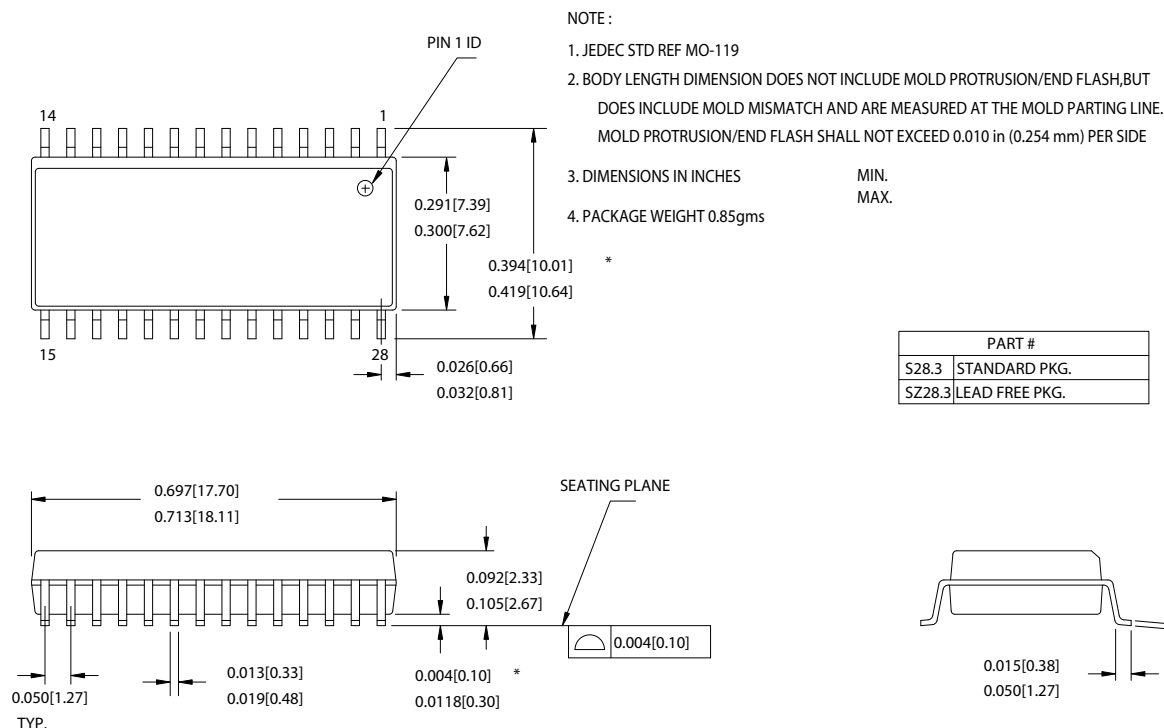
Ordering Information

All the parts below are Pb-Free.

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
25	CY22E016L-SZ25XCT	51-85026	28-pin SOIC	Commercial
	CY22E016L-SZ25XC	51-85026	28-pin SOIC	
25	CY22E016L-SZ25XIT	51-85026	28-pin SOIC	Industrial
	CY22E016L-SZ25XI	51-85026	28-pin SOIC	
35	CY22E016L-SZ35XCT	51-85026	28-pin SOIC	Commercial
	CY22E016L-SZ35XC	51-85026	28-pin SOIC	
35	CY22E016L-SZ35XIT	51-85026	28-pin SOIC	Industrial
	CY22E016L-SZ35XI	51-85026	28-pin SOIC	
45	CY22E016L-SZ45XCT	51-85026	28-pin SOIC	Commercial
	CY22E016L-SZ45XC	51-85026	28-pin SOIC	
45	CY22E016L-SZ45XIT	51-85026	28-pin SOIC	Industrial
	CY22E016L-SZ45XI	51-85026	28-pin SOIC	

Package Diagrams

28-Pin(300 Mil) Molded SOIC



51-85026-*D

Document History Page

Document Title: CY22E016L 16 Kbit (2K x 8) nvSRAM Document Number: 001-06727				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	427789	See ECN	TUP	New datasheet
*A	437321	See ECN	TUP	Show datasheet on external Web
*B	472053	See ECN	TUP	Updated Part Numbering Nomenclature and Ordering Information
*C	503290	See ECN	PCI	Converted from Advance to Preliminary Changed the term "Unlimited" to "Infinite" Removed Industrial Grade mention Corrected V_{IL} min specification from ($V_{CC} - 0.5$) to ($V_{SS} - 0.5$) Updated Part Nomenclature Table and Ordering Information Table
*D	1349963	See ECN	UHA/SFV	Changed from Preliminary to Final. Updated AC Test Conditions. Updated Ordering Information Table

© Cypress Semiconductor Corporation, 2007. The information contained herein is subject to change without notice. Cypress Semiconductor Corporation assumes no responsibility for the use of any circuitry other than circuitry embodied in a Cypress product. Nor does it convey or imply any license under patent or other rights. Cypress products are not warranted nor intended to be used for medical, life support, life saving, critical control or safety applications, unless pursuant to an express written agreement with Cypress. Furthermore, Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress products in life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Any Source Code (software and/or firmware) is owned by Cypress Semiconductor Corporation (Cypress) and is protected by and subject to worldwide patent protection (United States and foreign), United States copyright laws and international treaty provisions. Cypress hereby grants to licensee a personal, non-exclusive, non-transferable license to copy, use, modify, create derivative works of, and compile the Cypress Source Code and derivative works for the sole purpose of creating custom software and or firmware in support of licensee product to be used only in conjunction with a Cypress integrated circuit as specified in the applicable agreement. Any reproduction, modification, translation, compilation, or representation of this Source Code except as specified above is prohibited without the express written permission of Cypress.

Disclaimer: CYPRESS MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARD TO THIS MATERIAL, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE. Cypress reserves the right to make changes without further notice to the materials described herein. Cypress does not assume any liability arising out of the application or use of any product or circuit described herein. Cypress does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress' product in a life-support systems application implies that the manufacturer assumes all risk of such use and in doing so indemnifies Cypress against all charges.

Use may be limited by and subject to the applicable Cypress software license agreement.